



# GA6 'N\*', 5E'H<F I'GA6 'N&&\$5E'

## G i fZUWY' Ac i bh'NYbYf' 8]cXYg''

..... : YUhi fYg''

- Low profile package
- Ideal for automated placement
- Glass passivated chip junction
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C
- Part no. with suffix "Q" means AEC-Q101 qualified

.... AYW\Ub]WU'' 8UhU'

- DUW\_U[Y: DO-214AA (SMB)
- Molding compound meets UL 94 V-0 flammability rating, RoHS-compliant, halogen-free
- HYf a]bU'g': Tin plated leads, solderable per J-STD-002 and JESD22-B102
- Dc`Uf]hm. Cathode line denotes the cathode end

AUI]a i a'FUh]b[g (Ta=25 Unless otherwise specified)

D5F5A9H9F'	GMA6C@'	I B-H'	A5L'
DC power dissipation at T <sub>L</sub> = 75 °C	P <sub>D</sub>	W	3.0
Maximum instantaneous forward voltage@ I <sub>F</sub> =200mA	V <sub>F</sub>	V	1.5
Maximum junction temperature	T <sub>J</sub>		-55 to +150

Storage temperature range

T<sub>stg</sub>

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$$60\% = \$47 + 58 \quad 60\% = \$4$$

v2UGHULQJ ,QIRUPDWLRQ

35() (5(' 3 1	3\$&.,1* &2' (	81,7 : (, *+7 J	0,1,080 3\$&.\$*( SFV	287(5 &\$5721 48\$17,7< SFV	'(/,9(5< 02' (
60% = \$4 a60% =	\$4 )				

' UHH

v0DUNLQJ ,QIRUPDWLRQ

v2XWOLQH 'LPHQVLRQV

	'2	\$\$ 60%
	OLQ	OD
\$		

v 6XJJHVWHG SDG OD\RXW

